



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Katsumi Yamaguchi**
Serial No.: **10/087,556**
Filed: **03/01/2002**
For: **Semiconductor Device and Bump Formation Method**

TI No.: **31471**
Art Unit: **2811**
Examiner: **Im, Junghwa M.**
Conf. No.: **2191**

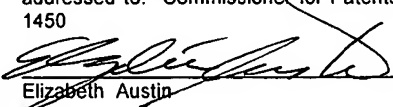
#11
Notice of Appeal

McMillan
8/4/03

NOTICE OF APPEAL

Commissioner For Patents
Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450	
 Elizabeth Austin	7/14/2003 Date

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Applicant hereby appeals to the Board of Appeals from the decision dated June 6, 2003, of the Primary Examiner finally rejecting Claims 1-6 and 9-22.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated
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Respectfully submitted,



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